

PRODUCT SPECIFICATION

Part Number PLH4020SA4-WCRGB1

Details

 \bullet 4.0 x 2.0 x 1.5mm Side View SMD RGB LED with integrated IC.

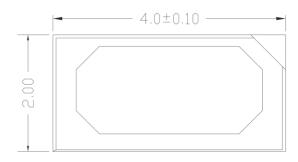
Applications

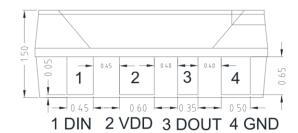
- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

Features

- 4020 with integrated high quality constant current IC and RGB LED chip.
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology number of LED stacked is not restricted.
- Cascading Enhancement Technology any 2 LED spacing can be up to 10 meters
- Data transfer rate of 800 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp.
- SA-I Anti-interference patent technology for single line data transmission.
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

Package Outline Dimensions & Pin Configuration





1.5±0.10

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is $\pm 0.2 \text{mm}$ unless otherwise noted

Note:

1. Specifications subject to change without notice





Pin Configuration

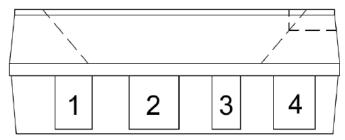


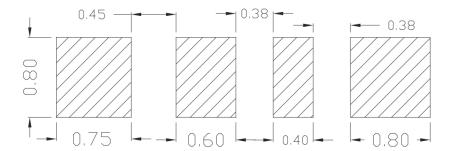
Figure 2. PLH4020SA4-WCRGB1 Pin Configuration

Notes

1. Dimension in millimeters, tolerance is ± 0.1 mm unless otherwise noted.

Number	Symbol	Function Description
1	DIN	Control data signal input
2	VDD	Power supply LED
3	DOUT	Control data signal output
4	GND	Ground

Recommended Soldering Pad Size



1 DIN 2 VDD 3 DOUT 4 GND



Absolute Maximum Rating (Ta = 25 °C, VSS=0V)

Parameter	Symbol	Range	Unit
Logic supply voltage	VDD	+3.5~+5.5	V
Logic input voltage	VIN	-0.5 ~VDD+0.5	V
Operating temperature	TOPT	− 45 ~ +85	°C
Storage temperature	TSTG	−50 ~ +150	°C
ESD pressure(HBM)	VESD	4K	V
ESD pressure(DM)	VESD	200	V

LED Characteristics $(Ta = 25^{\circ}C)$

Color	5n	nA	121	mA
Color	Wavelength(nm)	Light Intensity(mcd)	Wavelength(nm)	Light Intensity(mcd)
Red	620-630	50-150	620-630	300-500
Green	520-535	200-400	515-530	700-1500
Blue	460-475	50-100	460-475	200-300



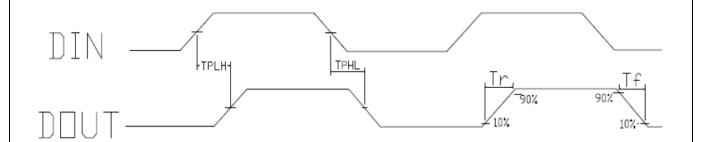
Recommended Operating Ranges (unless otherwise specified, $Ta = -20 \sim +70$ °C, $VDD = 4.5 \sim 5.5V, VSS = 0V$)

Parameter	Symbol	Min.	Тур.	Max	Unit	Test conditions
Supply voltage	V_{DD}	ı	5.2	-	V	-
R/G/B port pressure	$V_{DS,\;MAX}$	-	-	26	V	-
DOUT drive capability	ID_{OH}	-	49	-	mA	maximum source current
DOUT drive capability	ID_{OL}	-	-50	-	mA	maximum sink current
High level input voltage	V_{IH}	0.7*VDD	ı	-	V	VDD=5.0V
Low level input voltage	$V_{I\!L}$	1	1	0.3*VDD	V	VDD=5.0V
The frequency of PWM	F_{PWM}	1	1.2	1	KHZ	-
Static power consumption	I_{DD}	-	1	-	mA	-



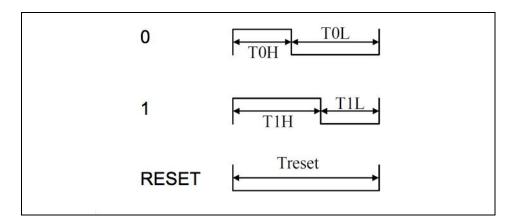
Switching Characteristics (unless otherwise specified, TA=25 °C)

Parameter	Symbol	Min.	Тур.	Max	Unit	Test conditions
The speed of data transmission	FDIN	-	800	-	KHZ	The duty ratio of 67% (data 1)
DOLUT to a consistent of the	TPLH	-	-	500	ns	
DOUT transmission delay	TPHL	-	-	500	ns	DIN→DOUT
IOLIT D. (D. T.	Tr	-	100	ı	ns	VDS=1.5V
IOUT Rise/Drop Time	Tf	-	100	-	ns	IOUT=5/13mA



Timing Waveforms

1. Input Code

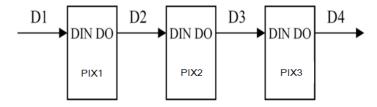




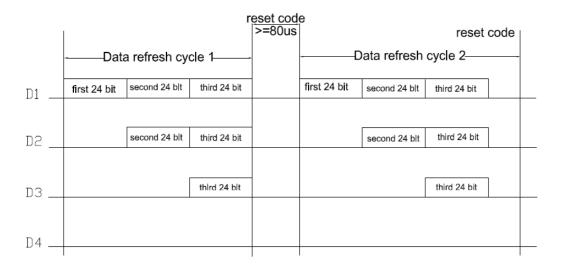
2. The data transmission time (TH+TL=1.25µs±600ns):

Name	Description	Min.	Typ. value	Max.	Unit
T	Period	1.2	-	-	μs
ТОН	0 code, high level time	0.2	0.32	0.4	μs
T0L	0 code, low level time	0.8	-	-	μs
T1H	1 code, high level time	0.62	0.64	1.0	μs
T1L	1 code, low level time	0.2	-	-	μs
Trst	Reset code, low level time	>80	-	-	μs

3. Connection Scheme



4. Data Transfer Format (Ta=25°C)



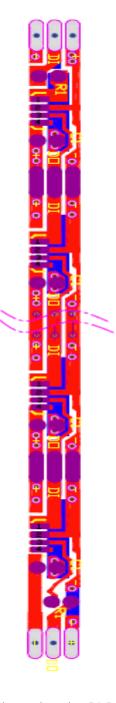
Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

5. 24-bit data format

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4
R3	R2	R1	RO	В7	В6	B5	B4	В3	B2	В1	ВО



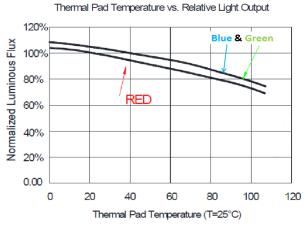
Typical Application Circuit



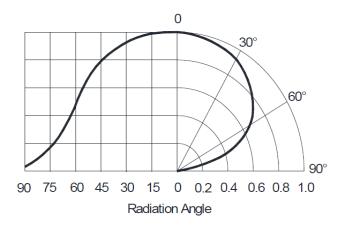
Product signal input and output must be connected in series with protection resistor R1. R1 depends on the size of the cascade amount, the greater the number of cascade, the smaller R1. The general recommended value is between $200\text{-}2K\Omega$, usually the recommended value is typical 500Ω .



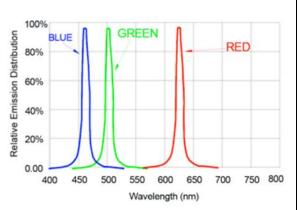
LED Performance Graph



Typical Radiation Pattern 120°



Wavelength Characteristics





Precautions

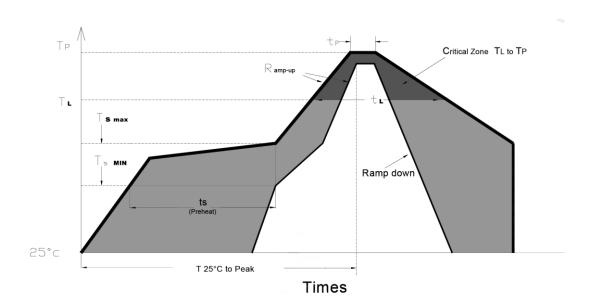
Please read the following notes before using the product:

- 1. Storage
- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.

1	1.4 After opening the package, the remaining LEDs should be kept in a resealed bag. 1.5 The LEDs require mandatory baking before usage. Baking treatment listed below. 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.											
×	*Baking treatment: 60±5°C for24 hours.											



2. Soldering Condition Recommended soldering conditions:



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate (Ts max to Tp)	3°C/second max.
Preheat: Temperature Min (Ts _{min})	150°C
Preheat: Temperature Min (Ts _{max})	200 °C
Preheat: Time (ts min to ts max)	60-180 seconds
Time Maintained Above: Temperature (T _L)	217 ℃
Time Maintained Above: Time (t L)	60-150 seconds
Peak/Classification Temperature (T P)	240 ℃
Time Within 5°C of Actual Peak Temperature (tp)	<10 seconds
Ramp-Down Rate	6°C/second max.
Time 25 °C to Peak Temperature	<6 minutes max.

Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

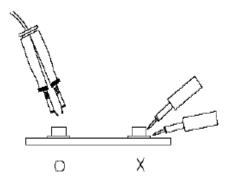


3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or antielectrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.Re: da



	Record of Revisions		
Rev.	Comments	Page	Date
0	Released Spec		4/27/202
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